

# CMP55N25/CMB55N25/CMI55N25/CMF55N25

250V, 69mΩ typ., 55A N-Channel MOSFET

## General Description

This Power MOSFET is produced using Cmos's advanced planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.

## Features

- 100% avalanche tested
- Improved dv/dt capability
- RoHS Compliant

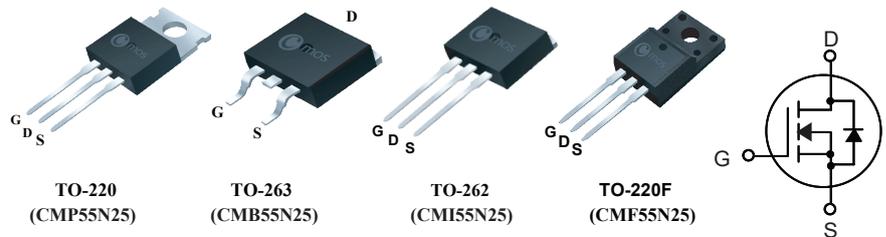
## Product Summary

BVDSS	R <sub>DS(on)</sub> max.	ID
250V	77mΩ	55A

## Applications

- Switching applications
- Synchronous Rectification

## TO-220/263/262/220F Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	220/263/262	220F	Units
V <sub>DS</sub>	Drain-Source Voltage	250		V
V <sub>GS</sub>	Gate-Source Voltage	±30		V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current	55	55*	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current	38	38*	A
I <sub>DM</sub>	Pulsed Drain Current	220	220*	A
EAS	Single Pulse Avalanche Energy (Note 1)	2102		mJ
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation	200	45	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150		°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150		°C

\* Drain current limited by maximum junction temperature.

## Thermal Data

Symbol	Parameter	220/263/262	220F	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient Max.	62	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case Max.	0.62	2.78	°C/W

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	250	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=25A$	---	69	77	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	---	4	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=250V, V_{GS}=0V$	---	---	1	μA
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	±100	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=25A$	---	32	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	1	---	Ω
$Q_g$	Total Gate Charge	$V_{DS}=200V, I_D=50A$ $V_{GS}=10V$	---	76	---	nC
$Q_{gs}$	Gate-Source Charge		---	20	---	
$Q_{gd}$	Gate-Drain Charge		---	25	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=125V, V_{GS}=10V, I_D=50A$ $R_G=25\Omega$	---	55	---	ns
$T_r$	Rise Time		---	50	---	
$T_{d(off)}$	Turn-Off Delay Time		---	212	---	
$T_f$	Fall Time		---	31	---	
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	---	4000	---	pF
$C_{oss}$	Output Capacitance		---	400	---	
$C_{riss}$	Reverse Transfer Capacitance		---	35	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Diode continuous forward current	$V_G=V_D=0V, \text{Force Current}$	---	---	55	A
$I_{S,pulse}$	Diode pulse current		---	---	220	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_F=25A, T_J=25^{\circ}\text{C}$	---	0.87	1.4	V

Note :

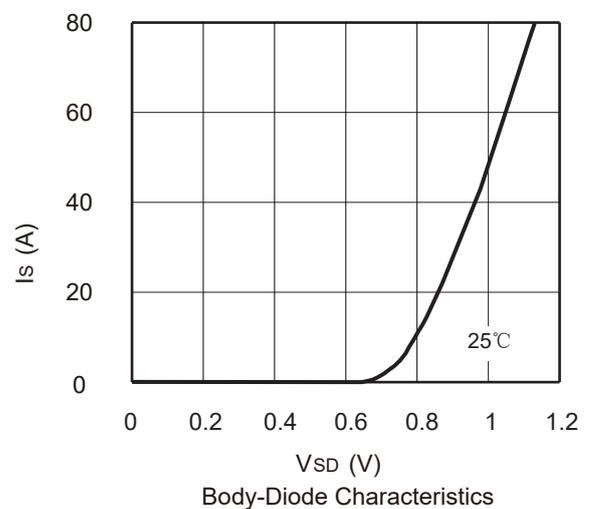
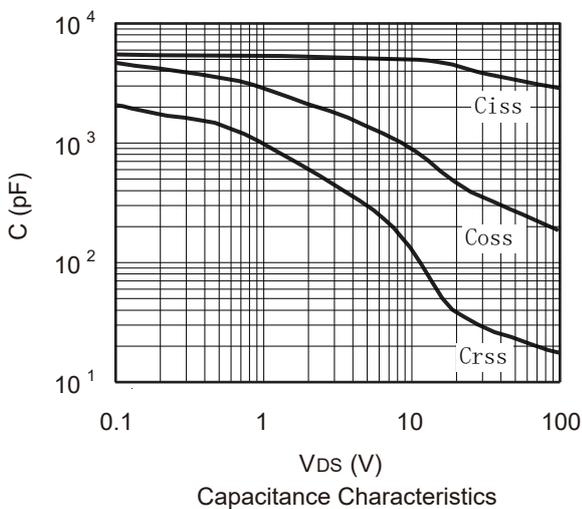
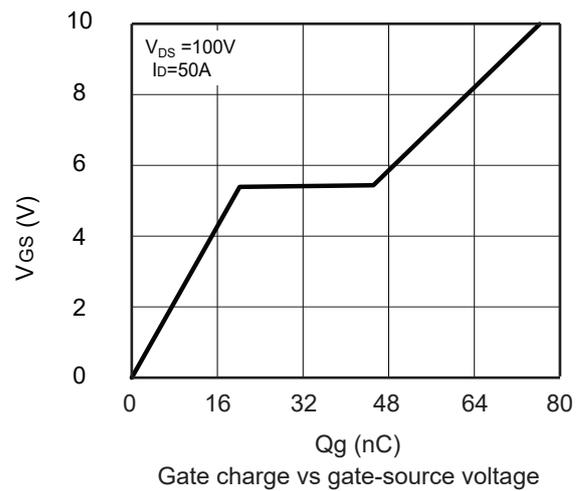
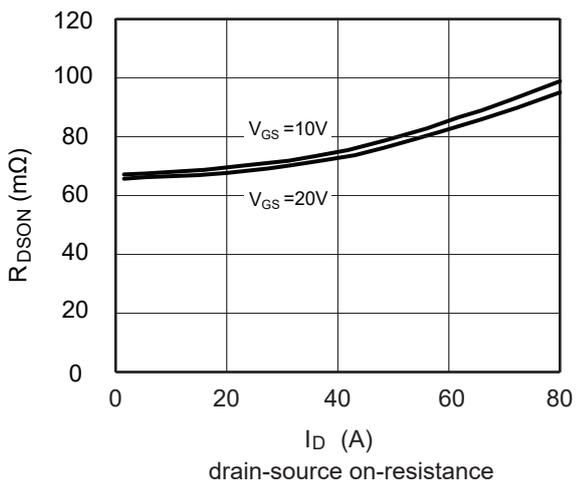
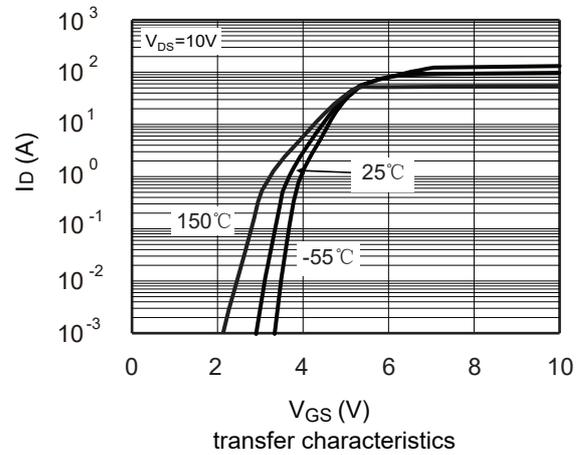
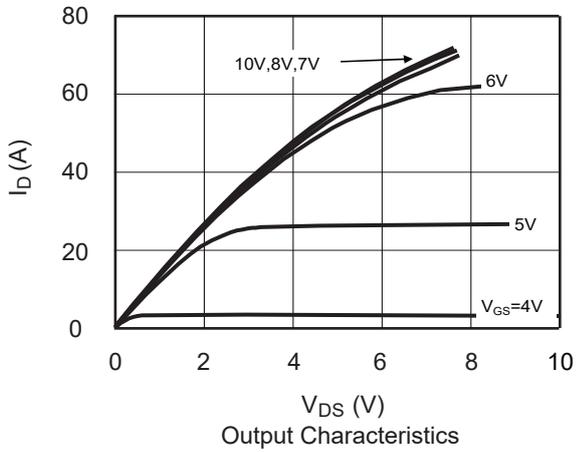
1.The EAS data shows Max. rating .The test condition is  $V_{DS}=80V, V_{GS}=10V, L=5\text{mH}, I_{AS}=29A$ .

This product has been designed and qualified for the consumer market.

Cmos assumes no liability for customers' product design or applications.

Cmos reserves the right to improve product design ,functions and reliability without notice.

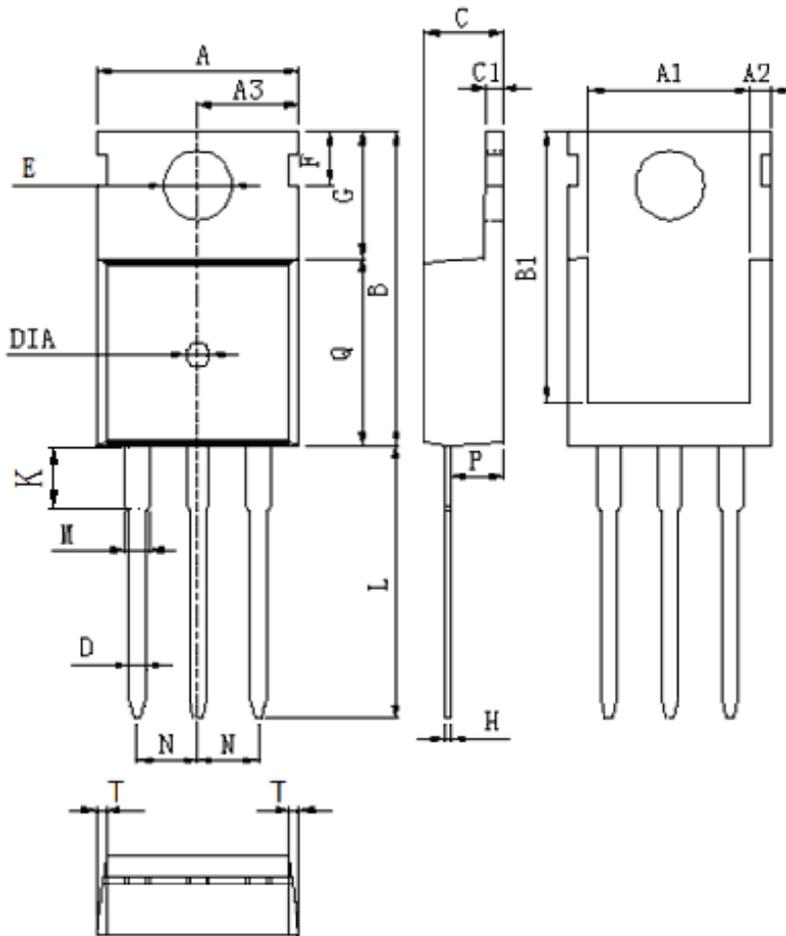
### Typical Characteristics



**Package Dimension**

TO-220

Unit :mm

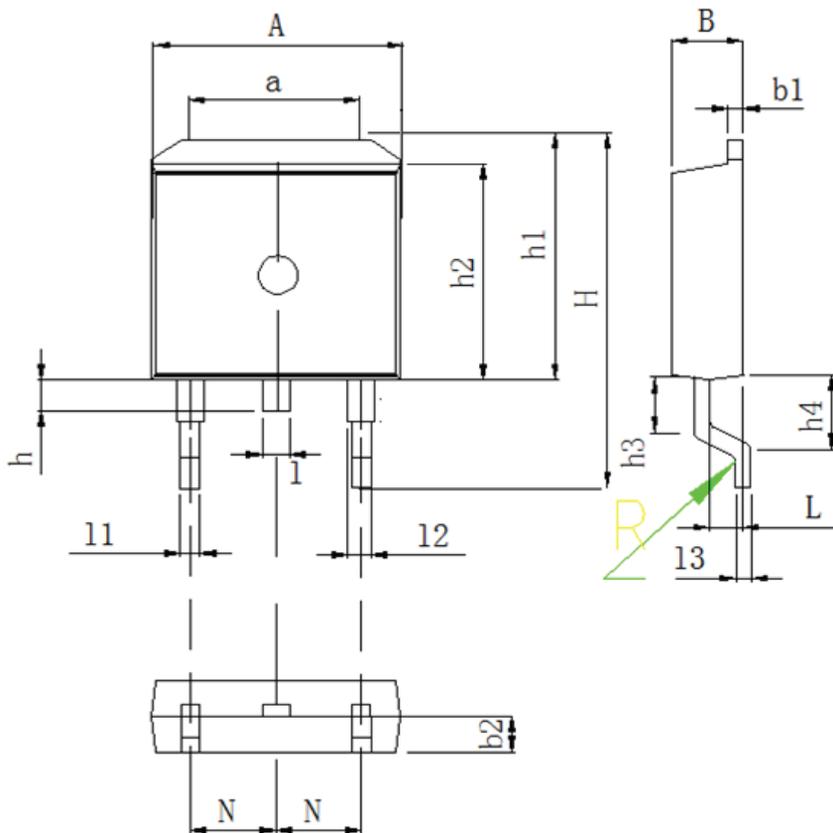


DIM	MILLIMETERS
A	10.0±0.3
A1	8.64±0.2
A2	1.15±0.1
A3	5.0±0.2
B	15.8±0.4
B1	13.2±0.3
C	4.56±0.1
C1	1.3±0.2
D	0.8±0.2
E	3.6±0.2
F	2.95±0.3
G	6.5±0.3
H	0.5±0.1
K	3.1±0.2
L	13.2±0.4
M	1.25±0.1
N	2.54±0.1
P	2.4±0.3
Q	9.0±0.3
T	W:0.35
DIA	⊙1.5(deep 0.2)

**Package Dimension**

TO-263

Unit :mm

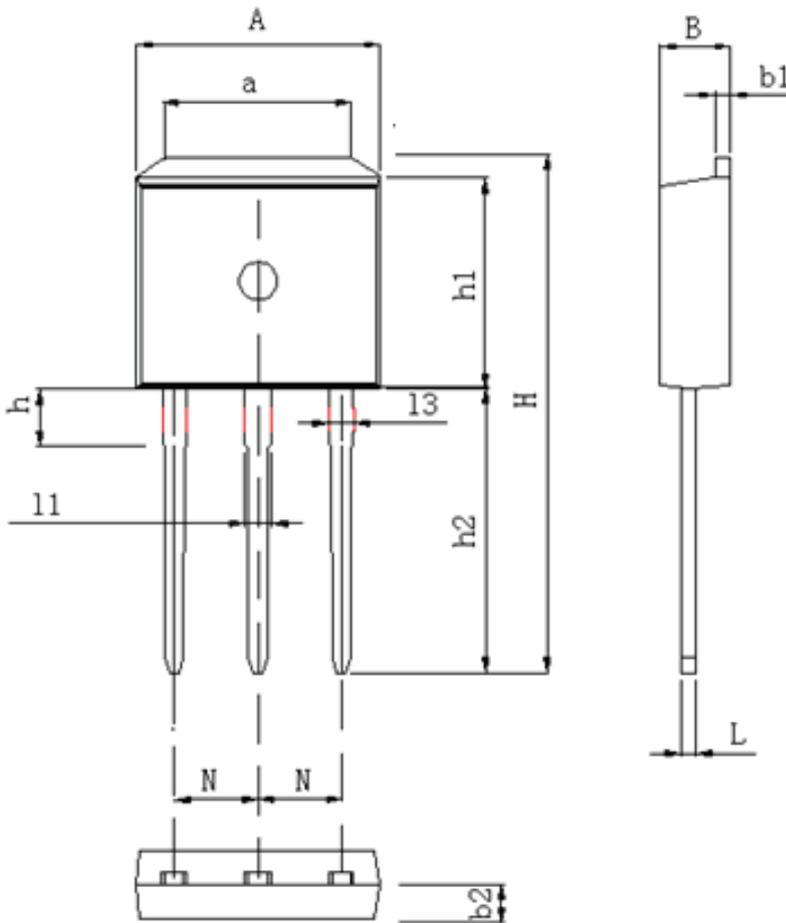


DIM	MILLIMETERS
A	$9.8 \pm 0.2$
a	$7.4 \pm 0.4$
B	$4.5 \pm 0.2$
b1	$1.3 \pm 0.05$
b2	$2.4 \pm 0.2$
H	$15.5 \pm 0.3$
h	$1.54 \pm 0.2$
h1	$10.5 \pm 0.2$
h2	$9.2 \pm 0.1$
h3	$1.54 \pm 0.2$
h4	$2.7 \pm 0.2$
L	$2.4 \pm 0.2$
1	$1.3 \pm 0.1$
11	$0.8 \pm 0.1$
12	$1.3 \pm 0.1$
13	$0.5 \pm 0.1$
N	$2.54 \pm 0.1$
R	$0.5R \pm 0.05$

**Package Dimension**

TO-262

Unit :mm

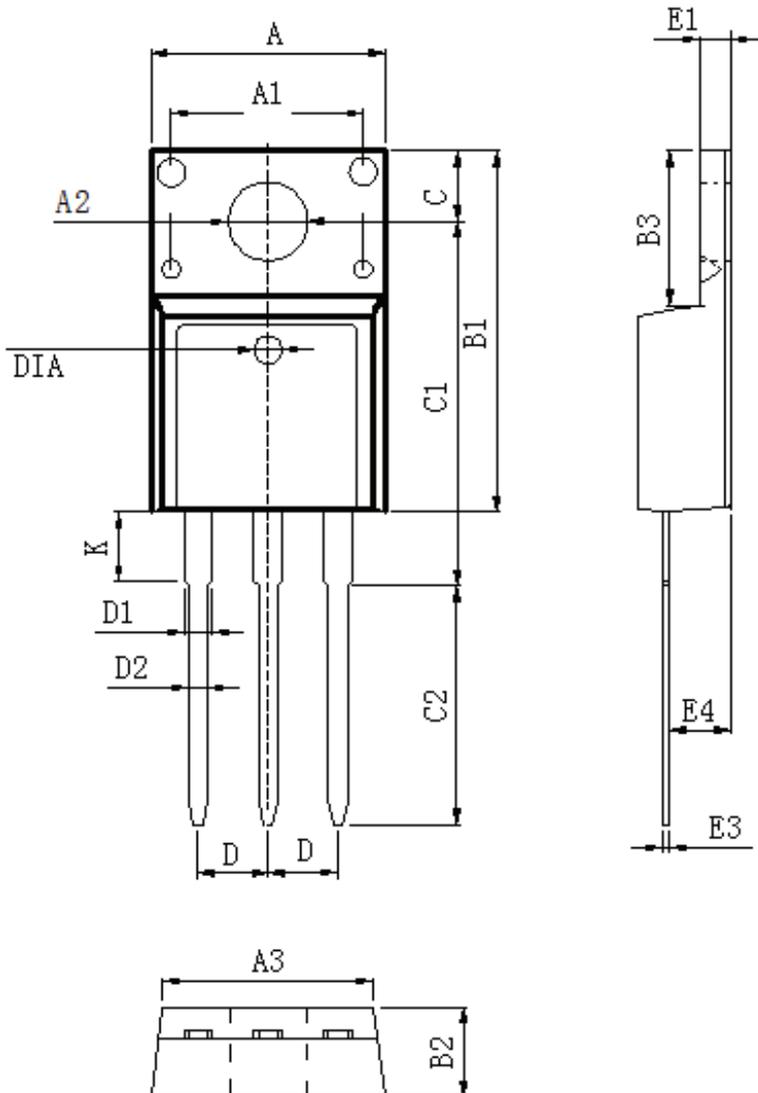


DIM	MILLIMETERS
A	$9.98 \pm 0.2$
a	$7.4 \pm 0.4$
B	$4.5 \pm 0.2$
b1	$1.3 \pm 0.05$
b2	$2.4 \pm 0.2$
H	$23.9 \pm 0.3$
h	$3.1 \pm 0.2$
h1	$9.16 \pm 0.2$
h2	$13.2 \pm 0.2$
L	$0.5 \pm 0.1$
l1	$1.3 \pm 0.1$
l2	$0.8 \pm 0.1$
N	$2.45 \pm 0.1$

**Package Dimension**

TO-220F

Unit :mm



DIM	MILLIMETERS
A	10.16±0.3
A1	7.00±0.1
A2	3.3±0.2
A3	9.5±0.2
B1	15.87±0.3
B2	4.7±0.2
B3	6.68±0.4
C	3.3±0.2
C1	12.57±0.3
C2	10.02±0.5
D	2.54±0.05
D1	1.28±0.2
D2	0.8±0.1
K	3.1±0.3
E1	2.54±0.1
E3	0.5±0.1
E4	2.76±0.2
DIA	⊙1.5 (deep 0.2)

